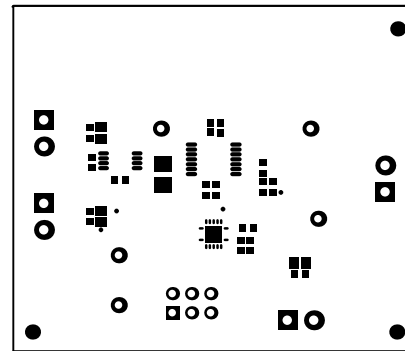
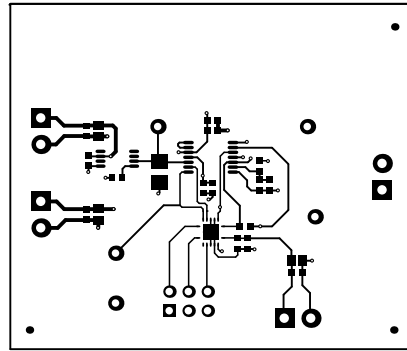


Logo2

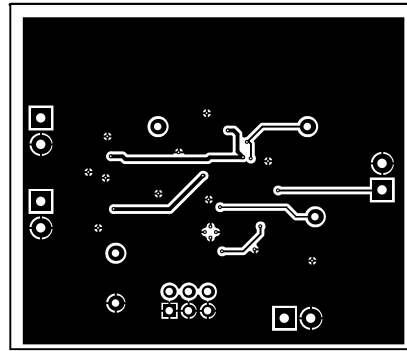

| | | | |
|----------------------------------|-----------------------|------------|--------------------------------|
| ALL ARTWORK VIEWED FROM TOP SIDE | BOARD #: TIPD192 | REV: E3 | SUN REV: Not In VersionControl |
| LAYER NAME = Top Overlay | TID #: TIPD192 | | |
| PLOT NAME = Top Overlay | GENERATED : 12/5/2016 | 2:23:48 PM | TEXAS INSTRUMENTS |



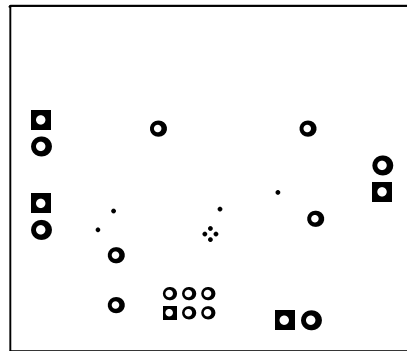
| | | | |
|----------------------------------|----------------------------------|-------------------|--------------------------------|
| ALL ARTWORK VIEWED FROM TOP SIDE | BOARD #: TIPD192 | REV: E3 | SUN REV: Not In VersionControl |
| LAYER NAME = Top Solder | TID #: TIPD192 | | |
| PLOT NAME = Top Solder Mask | GENERATED : 12/5/2016 2:23:49 PM | TEXAS INSTRUMENTS | |



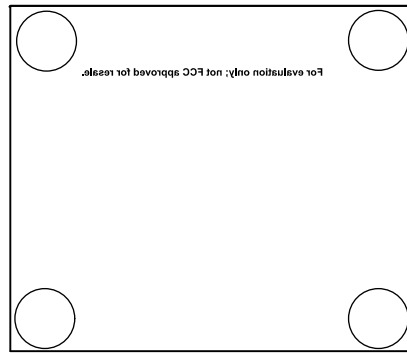
| | | | |
|----------------------------------|----------------------------------|-------------------|--------------------------------|
| ALL ARTWORK VIEWED FROM TOP SIDE | BOARD #: TIPD192 | REV: E3 | SUN REV: Not In VersionControl |
| LAYER NAME = Top Layer | TID #: TIPD192 | | |
| PLOT NAME = Top Layer | GENERATED : 12/5/2016 2:23:49 PM | TEXAS INSTRUMENTS | |



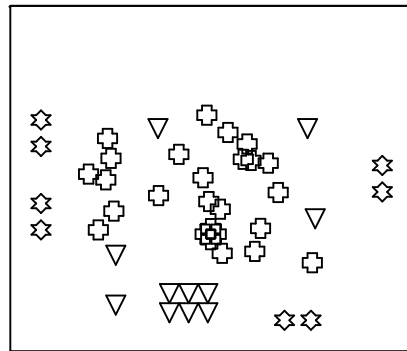
| | | | |
|----------------------------------|----------------------------------|-------------------|--------------------------------|
| ALL ARTWORK VIEWED FROM TOP SIDE | BOARD #: TIPD192 | REV: E3 | SUN REV: Not In VersionControl |
| LAYER NAME = Bottom Layer | TID #: TIPD192 | | |
| PLOT NAME = Bottom Layer | GENERATED : 12/5/2016 2:23:50 PM | TEXAS INSTRUMENTS | |



| | | | |
|----------------------------------|----------------------------------|-------------------|--------------------------------|
| ALL ARTWORK VIEWED FROM TOP SIDE | BOARD #: TIPD192 | REV: E3 | SUN REV: Not In VersionControl |
| LAYER NAME = Bottom Solder | TID #: TIPD192 | | |
| PLOT NAME = Bottom Solder Mask | GENERATED : 12/5/2016 2:23:51 PM | TEXAS INSTRUMENTS | |

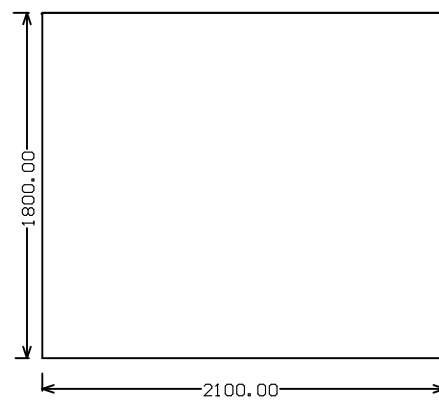


| | | | |
|----------------------------------|----------------------------------|-------------------|--------------------------------|
| ALL ARTWORK VIEWED FROM TOP SIDE | BOARD #: TIPD192 | REV: E3 | SUN REV: Not In VersionControl |
| LAYER NAME = Bottom Overlay | TID #: TIPD192 | | |
| PLOT NAME = Bottom Overlay | GENERATED : 12/5/2016 2:23:52 PM | TEXAS INSTRUMENTS | |



| Symbol | Quantity | Finished Hole Size | Plated | Hole Type |
|--------|----------|--------------------|--------|-----------|
| ⊙ | 26 | 16.00mil (0.254mm) | PTH | Round |
| ▽ | 11 | 40.00mil (1.016mm) | PTH | Round |
| ☆ | 8 | 50.00mil (1.270mm) | PTH | Round |
| | 45 Total | | | |

| | | | |
|----------------------------------|-----------------------|------------|--------------------------------|
| ALL ARTWORK VIEWED FROM TOP SIDE | BOARD #: TIPD192 | REV: E3 | SUN REV: Not In VersionControl |
| LAYER NAME = Drill Drawing | TID #: TIPD192 | | |
| PLOT NAME = Drill Drawing | GENERATED : 12/5/2016 | 2:23:53 PM | TEXAS INSTRUMENTS |



| | | | |
|----------------------------------|-----------------------|------------|--------------------------------|
| ALL ARTWORK VIEWED FROM TOP SIDE | BOARD #: TIPD192 | REV: E3 | SUN REV: Not In VersionControl |
| LAYER NAME = M2 Board Dimensions | TID #: TIPD192 | | |
| PLOT NAME = Board Dimensions | GENERATED : 12/5/2016 | 2:23:54 PM | TEXAS INSTRUMENTS |

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Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265
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